ABSTRACT OF THE DISCLOSURE

A copper alloy that consists essentially of, by weight, from 0.15% to 0.7% of chromium, from 0.005% to 0.3% of silver, from 0.01% to 0.15% of titanium, from 0.01% to 0.10% of silicon, up to 0.2% of iron, up to 0.5% of tin, and the balance copper and inevitable impurities has high strength, a yield strength in excess of 80 ksi, and high electrical conductivity, in excess of 80% IACS. The alloy further has substantially isotropic bend characteristics when the processing route includes a solution heat anneal above 850°C and subsequent cold rolling into sheet, strip or foil interspersed by bell annealing. As a result, the alloy is particularly suited for forming into box-type electrical connectors for both automotive or multimedia applications. The alloy is also suitable for forming into a rod, wire or section.